Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	12198	(wafer or substrate or target) near5 (heat or temperature or thermal) near4 (absorb$4 or sink or adsorb$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 08:58
L2	27583	(wafer or substrate or target) near8 (heat or temperature or light or radiation or beam or thermal) near4 (absorb$4 or sink or adsorb$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 09:08
L3	2206	2 same ((wafer or substrate) near3 (stage or position$4 or support$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 09:09
L4	65	3 and ((thermal or heat or temperature) adj3 (insulat$4) adj4 (member or element or layer or film or plate))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 09:18
L5	7	"6163365"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/23 09:19
L6	25	"6268904"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/23 09:23
L7	6	"6259509"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/23 09:25
L8	3357	2 and ("355"/$.ccls. or "250"/$.ccls. or "356"/$.ccls. or "378"/$.ccls. or "430"/$.ccls.)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/23 10:37
L9	637	8 and projection	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/23 09:27
L10	452	9 and (mask or reticle)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/23 09:27

L11	142	10 and ((cool$4 or releas$ or reduc$4) near4 (heat or temperature or thermal))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 09:34
L12	2962	((light or radiation or beam or ray) near4 (absorb$4 or adsorb$4)) same ((wafer or substrate or mask or object or target or reticle) near3 (stage or position$4 or support$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 09:38
L13	669	((light or radiation or beam or ray) near4 (absorb$4 or adsorb$4)) near7 ((wafer or substrate or mask or object or target or reticle) near3 (stage or position$4 or support$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 09:38
L14	273	13 and ("355"/$.ccls. or "250"/$.ccls. or "356"/$.ccls. or "378"/$.ccls. or "430"/$.ccls.)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 09:39
L15	57	14 and projection	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/23 09:50
L16	222	((light or radiation or beam or ray) near4 (absorb$4 or adsorb$4)) near5 (position$4 or plac$4 or displac$4 or form$4) near6 ((insulat$4 adj3 (layer or film or element or device or plate)) or (cool$4 adj4 (device or system or element or apparatus)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 09:58
L17	4	16 and ((light or ray or beam or radiation) near4 (reflectivity))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 09:55
L18	50	16 and ($4lithograph$6 or exposure)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 10:01
L19	17328	((wafer or substrate or reticle or mask) same (light or beam or ray or radiation) near5 ((absorber or adsorber) or ((absorb$4 or adsorb$4) near4 (element or device or plate or member or layer or film or apparatus))))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 10:05

L20	894	(((wafer or substrate or reticle or mask) adj4 (stage or position$4 or hold$4 or support$4)) same (light or beam or ray or radiation) near5 ((absorber or adsorber) or ((absorb$4 or adsorb$4) near4 (element or device or plate or member or layer or film or apparatus))))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 10:08
L21	875	20 and ((light or beam or ray or radiation) near5 (absorb$4 or adsorb$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 10:09
L23	28	21 and ((thermal or heat or temperature) near4 (insulat$4) near4 (layer or film or plate or member or element))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/23 10:13
L24	203	21 and (((reticle or mask or substrate or wafer) adj4 (stage or chuck)) or ((position$4 or hold$4 or support$4) adj3 (device or system or apparatus)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 10:16
L25	164	24 and (projection or optical or lens or $4lithograph$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 10:19
L26	122	25 and (thermal or heat or temperature)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 10:32
L27	2637	((substrate or wafer) near4 (stage or chuck or hold$4 or support$4)) same ((light or beam or ray or radiation) near4 (absorb$4 or adsorb$4 or absorpt$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 10:36
L28	536	((substrate or wafer) near4 (stage or chuck or hold$4 or support$4)) near7 ((light or beam or ray or radiation) near4 (absorb$4 or adsorb$4 or absorpt$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 10:37
L29	210	28 and ("355"/$.ccls. or "250"/$.ccls. or "356"/$.ccls. or "378"/$.ccls. or "430"/$.ccls.)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 10:39

| L30 | 47 | 29 and ((wafer or substrage) adj3 (stage or hold$4 or support$4 or chuck)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/23 10:40 |